

P/N: KP-1608MGCK

MEGA GREEN

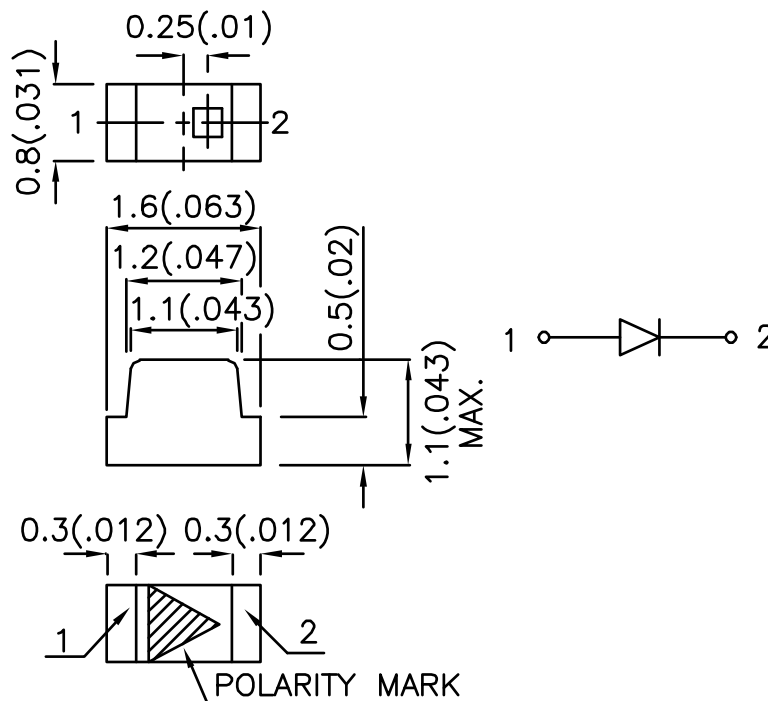
Features

- 1.6mmX0.8mm SMT LED, 1.1mm THICKNESS.
- LOW POWER CONSUMPTION.
- WIDE VIEWING ANGLE.
- IDEAL FOR BACKLIGHT AND INDICATOR.
- VARIOUS COLORS AND LENS TYPES AVAILABLE.
- PACKAGE: 2000PCS / REEL.
- MOISTURE SENSITIVITY LEVEL : LEVEL 3 .
- RoHS COMPLIANT.

Description

The Mega Green source color devices are made with DH InGaAlP on GaAs substrate Light Emitting Diode.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ± 0.1 (0.004") unless otherwise noted.
3. Specifications are subject to change without notice.

Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Typ.	2 θ 1/2
KP-1608MGCK	MEGA GREEN (InGaAlP)	WATER CLEAR	18	60	120°

Notes:

1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.
2. Luminous Intensity / Luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ_{peak}	Peak Wavelength	Mega Green	574		nm	IF=20mA
λ_D [1]	Dominant Wavelength	Mega Green	570		nm	IF=20mA
$\Delta\lambda_{1/2}$	Spectral Line Half-width	Mega Green	20		nm	IF=20mA
C	Capacitance	Mega Green	15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Mega Green	2.1	2.5	V	IF=20mA
IR	Reverse Current	Mega Green		10	uA	VR = 5V

Notes:

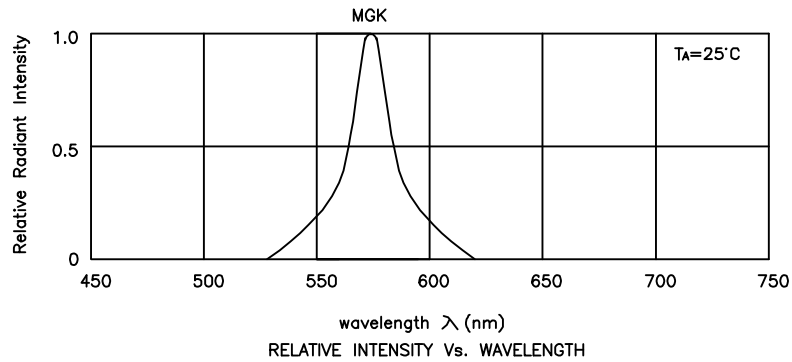
1. Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

Parameter	Mega Green	Units
Power dissipation	105	mW
DC Forward Current	30	mA
Peak Forward Current [1]	150	mA
Reverse Voltage	5	V
Operating/Storage Temperature	-40°C To +85°C	

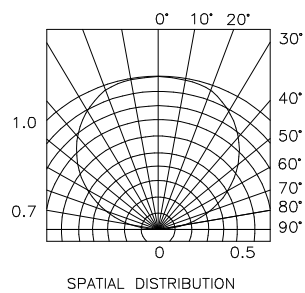
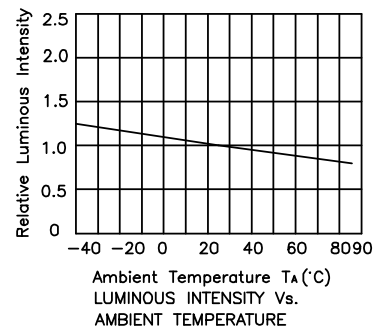
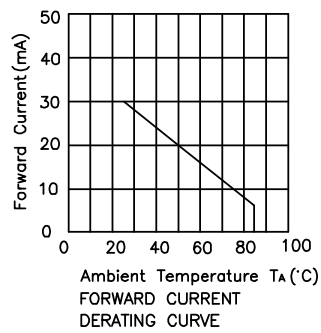
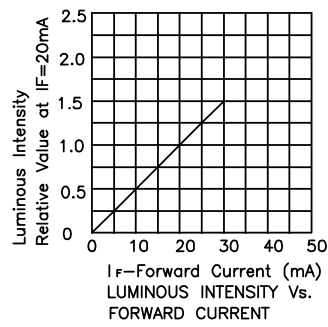
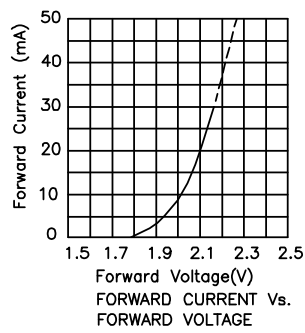
Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.



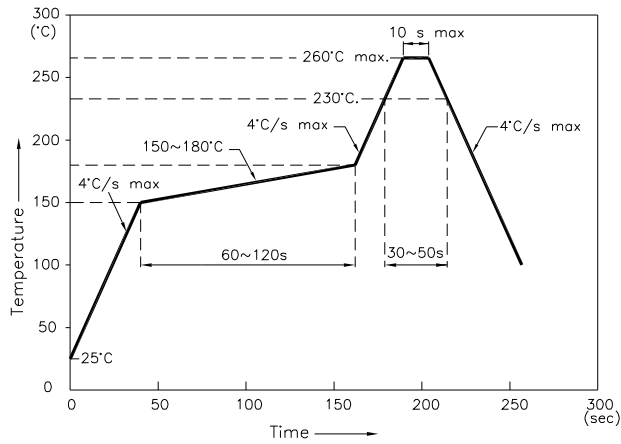
Mega Green

KP-1608MGCK



KP-1608MGCK

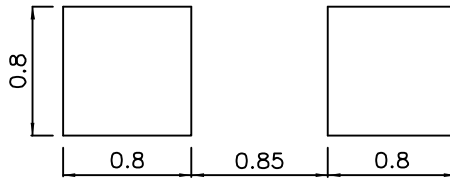
Reflow Soldering Profile For Lead-free SMT Process.



NOTES:

1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units : mm)



Tape Specifications (Units : mm)

